FAIRCHILD SEMICONDUCTOR®

June 2009

FOD3120
High Noise Immunity, 2.5A Output Current, Gate Drive Optocoupler

Features

- High noise immunity characterized by 35kV/μs minimum common mode rejection
- 2.5A peak output current driving capability for most 1200V/20A IGBT
- Use of P-channel MOSFETs at output stage enables output voltage swing close to the supply rail
- Wide supply voltage range from 15V to 30V
- Fast switching speed
  - 400ns max. propagation delay
  - 100ns max. pulse width distortion
- Under Voltage LockOut (UVLO) with hysteresis
- Extended industrial temperate range, -40°C to 100°C temperature range
- Safety and regulatory approved
  - UL1577, 5000 V_{RMS} for 1 min.
  - IEC60747-5-2
- $R_{DS(ON)}$ of 1Ω (typ.) offers lower power dissipation
- >8.0mm clearance and creepage distance (option 'T' or 'TS')
- 1,414V Peak Working Insulation Voltage (V_{IORM})

Applications

- Industrial inverter
- Uninterruptible power supply
- Induction heating
- Isolated IGBT/Power MOSFET gate drive

Description

The FOD3120 is a 2.5A Output Current Gate Drive Optocoupler, capable of driving most 1200V/20A IGBT/MOSFET. It is ideally suited for fast switching driving of power IGBT and MOSFETs used in motor control inverter applications, and high performance power system.

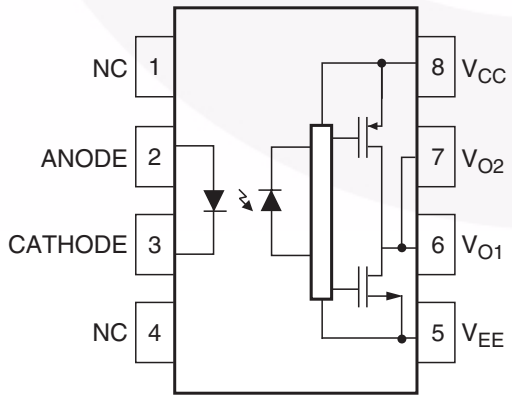
It utilizes Fairchild's patented coplanar packaging technology, Optoplanar®, and optimized IC design to achieve high noise immunity, characterized by high common mode rejection.

It consists of a gallium aluminum arsenide (AlGaAs) light emitting diode optically coupled to an integrated circuit with a high-speed driver for push-pull MOSFET output stage.

Related Resources

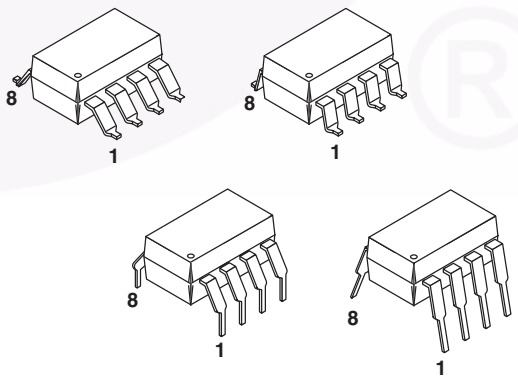
- FOD3150, 1A Output Current, Gate Drive Optocoupler Datasheet
- www.fairchildsemi.com/products/opto/

Functional Block Diagram



Note:
A 0.1μF bypass capacitor must be connected between pins 5 and 8.

Package Outlines



Truth Table

LED	$V_{CC} - V_{EE}$ "Positive Going" (Turn-on)	$V_{CC} - V_{EE}$ "Negative Going" (Turn-off)	V_O
Off	0V to 30V	0V to 30V	Low
On	0V to 11.5V	0V to 10V	Low
On	11.5V to 13.5V	10V to 12V	Transition
On	13.5V to 30V	12V to 30V	High

Pin Definitions

Pin #	Name	Description
1	NC	Not Connected
2	Anode	LED Anode
3	Cathode	LED Cathode
4	NC	Not Connected
5	V_{EE}	Negative Supply Voltage
6	V_{O2}	Output Voltage 2 (internally connected to V_{O1})
7	V_{O1}	Output Voltage 1
8	V_{CC}	Positive Supply Voltage

Safety and Insulation Ratings

As per IEC 60747-5-2. This optocoupler is suitable for “safe electrical insulation” only within the safety limit data. Compliance with the safety ratings shall be ensured by means of protective circuits.

Symbol	Parameter	Min.	Typ.	Max.	Unit
	Installation Classifications per DIN VDE 0110/1.89 Table 1				
	For Rated Mains Voltage < 150Vrms		I–IV		
	For Rated Mains Voltage < 300Vrms		I–IV		
	For Rated Mains Voltage < 450Vrms		I–III		
	For Rated Mains Voltage < 600Vrms		I–III		
	For Rated Mains Voltage < 1000Vrms (Option T, TS)		I–III		
	Climatic Classification		40/100/21		
	Pollution Degree (DIN VDE 0110/1.89)		2		
CTI	Comparative Tracking Index	175			
V_{PR}	Input to Output Test Voltage, Method b, V_{IORM} x 1.875 = V_{PR}, 100% Production Test with tm = 1 sec., Partial Discharge < 5pC	2651			
	Input to Output Test Voltage, Method a, V_{IORM} x 1.5 = V_{PR}, Type and Sample Test with tm = 60 sec.,Partial Discharge < 5 pC	2121			
V_{IORM}	Max Working Insulation Voltage	1,414			V_{peak}
V_{IOTM}	Highest Allowable Over Voltage	6000			V_{peak}
	External Creepage	8			mm
	External Clearance	7.4			mm
	External Clearance (for Option T or TS - 0.4” Lead Spacing)	10.16			mm
	Insulation Thickness	0.5			mm
	Safety Limit Values – Maximum Values Allowed in the Event of a Failure				
T_{Case}	Case Temperature	150			°C
$I_{S,INPUT}$	Input Current	25			mA
$P_{S,OUTPUT}$	Output Power (Duty Factor ≤ 2.7%)	250			mW
R_{IO}	Insulation Resistance at T_S, V_{IO} = 500V	10^9			Ω

Absolute Maximum Ratings (T_A = 25ºC unless otherwise specified)

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Value	Units
T_{STG}	Storage Temperature	-55 to +125	ºC
T_{OPR}	Operating Temperature	-40 to +100	ºC
T_J	Junction Temperature	-40 to +125	ºC
T_{SOL}	Lead Wave Solder Temperature (refer to page 19 for reflow solder profile)	260 for 10sec	ºC
$I_{F(AVG)}$	Average Input Current	25	mA
V_R	Reverse Input Voltage	5	V
$I_{O(PEAK)}$	Peak Output Current(1)	3.0	A
$V_{CC} - V_{EE}$	Supply Voltage	0 to 35	V
$V_{O(PEAK)}$	Peak Output Voltage	0 to V_{CC}	V
$t_{R(IN)}$, $t_{F(IN)}$	Input Signal Rise and Fall Time	500	ns
PD_I	Input Power Dissipation(2)(4)	45	mW
PD_O	Output Power Dissipation(3)(4)	250	mW

Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to absolute maximum ratings.

Symbol	Parameter	Value	Units
T_A	Ambient Operating Temperature	-40 to +100	°C
$V_{CC} - V_{EE}$	Power Supply	15 to 30	V
$I_{F(ON)}$	Input Current (ON)	7 to 16	mA
$V_{F(OFF)}$	Input Voltage (OFF)	0 to 0.8	V

Isolation Characteristics

Apply over all recommended conditions, typical value is measured at T_A = 25ºC

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Units
V_{ISO}	Input-Output Isolation Voltage	T_A = 25ºC, R.H.< 50%, t = 1.0min, $I_{I-O} \leq$ 10µA, 50Hz(5)(6)	5000			V_{RMS}
R_{ISO}	Isolation Resistance	V_{I-O} = 500V(5)		10^{11}		Ω
C_{ISO}	Isolation Capacitance	V_{I-O} = 0V, Freq = 1.0MHz(5)		1		pF

Electrical Characteristics

Apply over all recommended conditions, typical value is measured at V_{CC} = 30V, V_{EE} = Ground, T_A = 25°C unless otherwise specified.

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Units
V_F	Input Forward Voltage	I_F = 10mA	1.2	1.5	1.8	V
$\Delta(V_F / T_A)$	Temperature Coefficient of Forward Voltage			-1.8		mV/ºC
BV_R	Input Reverse Breakdown Voltage	I_R = 10µA	5			V
C_{IN}	Input Capacitance	f = 1MHz, VF = 0V		60		pF
I_{OH}	High Level Output Current(1)	$V_O = V_{CC} – 3V$	-1	-2.0	-2.5	A
		$V_O = V_{CC} – 6V$	-2.0		-2.5	
I_{OL}	Low Level Output Current(1)	$V_O = V_{EE} + 3V$	1	2.0	2.5	A
		$V_O = V_{EE} + 6V$	2.0		2.5	
V_{OH}	High Level Output Voltage	I_F = 10mA, I_O = -2.5A	$V_{CC} – 6.25V$	$V_{CC} – 2.5V$		V
		I_F = 10mA, I_O = -100mA	$V_{CC} – 0.25V$	$V_{CC} – 0.1V$		
V_{OL}	Low Level Output Voltage	I_F = 0mA, I_O = 2.5A		$V_{EE} + 2.5V$	$V_{EE} + 6.25V$	V
		I_F = 0mA, I_O = 100mA		$V_{EE} + 0.1V$	$V_{EE} + 0.25V$	
I_{CCH}	High Level Supply Current	V_O = Open, I_F = 7 to 16mA		2.8	3.8	mA
I_{CCL}	Low Level Supply Current	V_O = Open, V_F = 0 to 0.8V		2.8	3.8	mA
I_{FLH}	Threshold Input Current Low to High	I_O = 0mA, V_O > 5V		2.3	5.0	mA
V_{FHL}	Threshold Input Voltage High to Low	I_O = 0mA, V_O < 5V	0.8			V
V_{UVLO+}	Under Voltage Lockout Threshold	I_F = 10mA, V_O > 5V	11.5	12.7	13.5	V
$V_{UVLO–}$		I_F = 10mA, V_O < 5V	10.0	11.2	12.0	V
$UVLO_{HYS}$	Under Voltage Lockout Threshold Hysteresis			1.5		V

Switching Characteristics

Apply over all recommended conditions, typical value is measured at V_{CC} = 30V, V_{EE} = Ground, T_A = 25°C unless otherwise specified.

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Units
t_{PHL}	Propagation Delay Time to Logic Low Output	I_F = 7mA to 16mA, Rg = 10Ω, Cg =10nF, f = 10kHz, Duty Cycle = 50%	150	275	400	ns
t_{PLH}	Propagation Delay Time to Logic High Output		150	255	400	ns
PWD	Pulse Width Distortion, $\lvert t_{PHL} - t_{PLH} \rvert$			20	100	ns
PDD (Skew)	Propagation Delay Difference Between Any Two Parts or Channels, $(t_{PHL} - t_{PLH})$[7]		-250		250	ns
t_r	Output Rise Time (10% – 90%)			60		ns
t_f	Output Fall Time (90% – 10%)			60		ns
$t_{UVLO\ ON}$	UVLO Turn On Delay	I_F = 10mA , V_O > 5V		1.6		µs
$t_{UVLO\ OFF}$	UVLO Turn Off Delay	I_F = 10mA , V_O < 5V		0.4		µs
$\lvert CM_H \rvert$	Common Mode Transient Immunity at Output High	T_A = 25°C, V_{CC} = 30V, I_F = 7 to 16mA, V_{CM} = 2000V[8]	35	50		kV/µs
$\lvert CM_L \rvert$	Common Mode Transient Immunity at Output Low	T_A = 25°C, V_{CC} = 30V, V_F = 0V, V_{CM} = 2000V[9]	35	50		kV/µs

Notes:

1. Maximum pulse width = 10µs, maximum duty cycle = 1.1%
2. Derate linearly above 87°C, free air temperature at a rate of 0.77mW/°C
3. No derating required across temperature range.
4. Functional operation under these conditions is not implied. Permanent damage may occur if the device is subjected to conditions outside these ratings.
5. Device is considered a two terminal device: Pins 2 and 3 are shorted together and Pins 5, 6, 7 and 8 are shorted together.
6. 5,000 V_{RMS} for 1 minute duration is equivalent to 6,000 VAC_{RMS} for 1 second duration.
7. The difference between t_{PHL} and t_{PLH} between any two FOD3120 parts under same test conditions.
8. Common mode transient immunity at output high is the maximum tolerable negative dVcm/dt on the trailing edge of the common mode impulse signal, Vcm, to assure that the output will remain high (i.e. V_O > 15.0V).
9. Common mode transient immunity at output low is the maximum tolerable positive dVcm/dt on the leading edge of the common pulse signal, Vcm, to assure that the output will remain low (i.e. V_O < 1.0V).

Typical Performance Curves

Fig. 1 Output High Voltage Drop vs. Output High Current

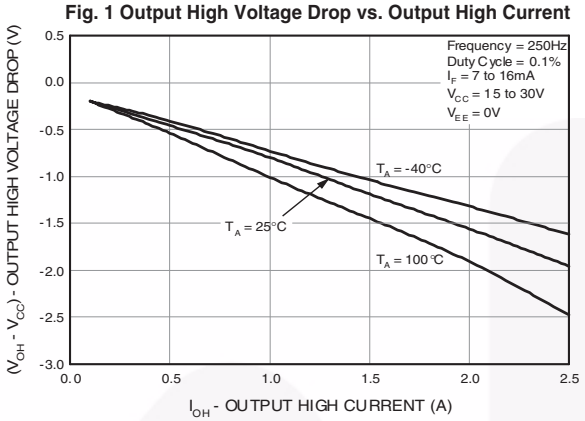


Fig. 2 Output High Voltage Drop vs. Ambient Temperature

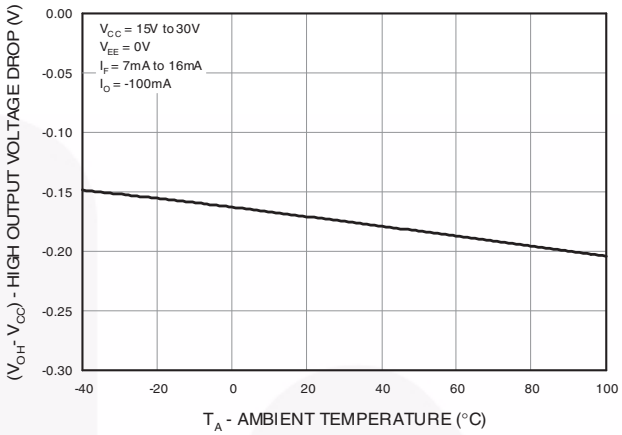


Fig. 3 Output High Current vs. Ambient Temperature

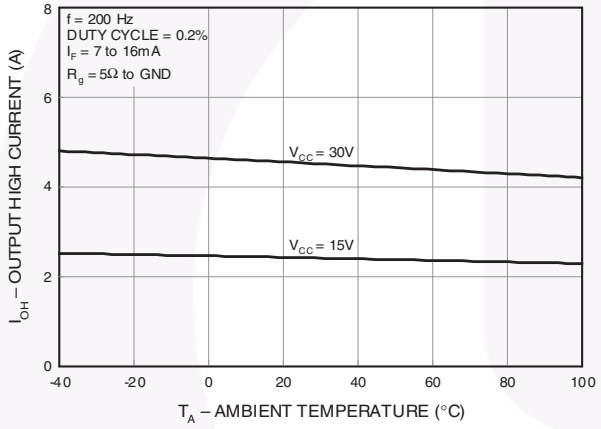


Fig. 4 Output High Current vs. Ambient Temperature

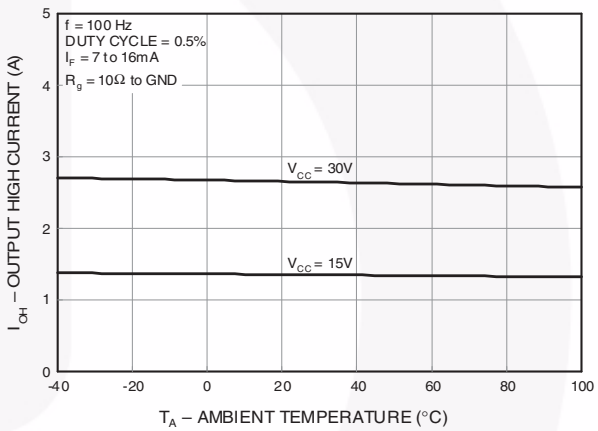


Fig. 5 Output Low Voltage vs. Output Low Current

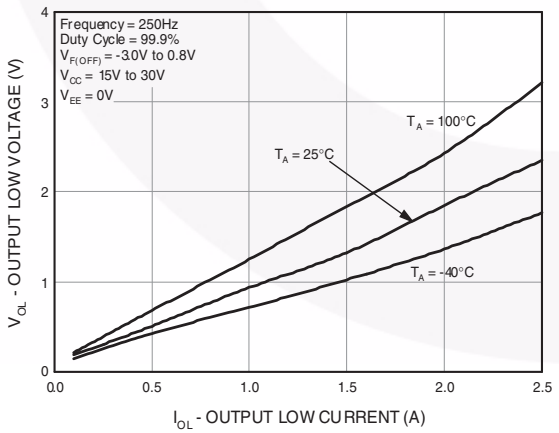
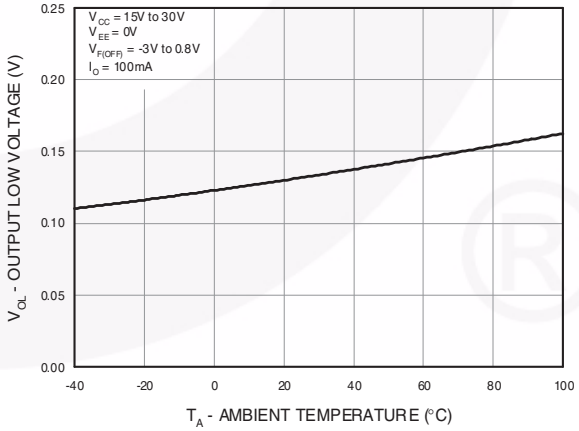


Fig. 6 Output Low Voltage vs. Ambient Temperature



Typical Performance Curves (Continued)

Fig. 7 Output Low Current vs. Ambient Temperature

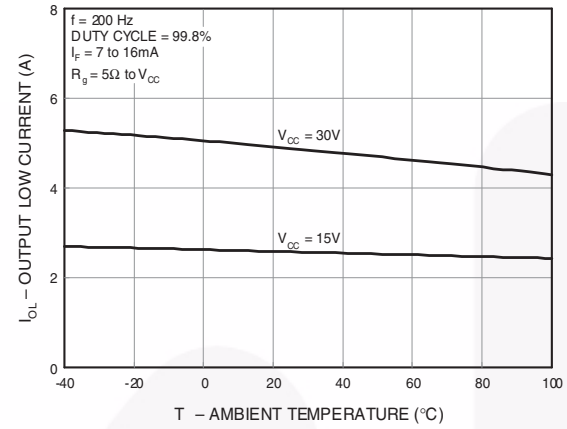


Fig. 8 Output Low Current vs. Ambient Temperature

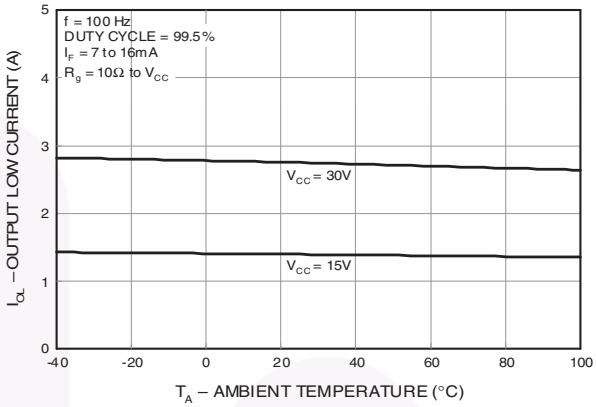


Fig. 9 Supply Current vs. Ambient Temperature

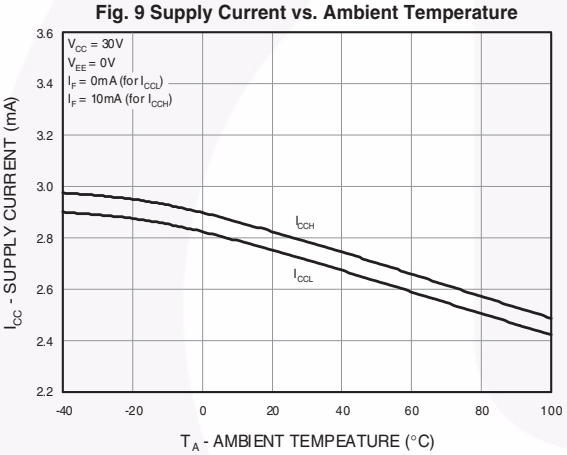


Fig. 10 Supply Current vs. Supply Voltage

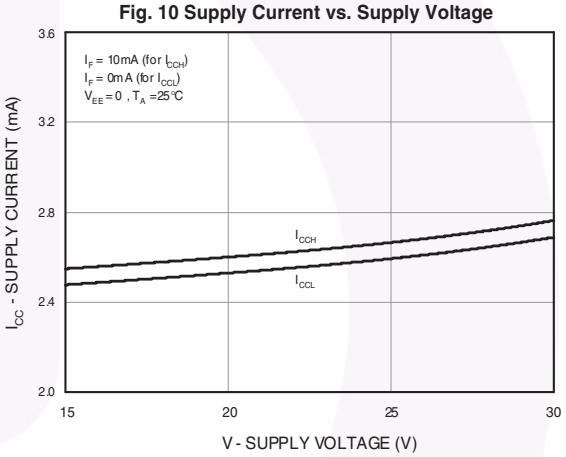


Fig. 11 Low to High Input Current Threshold vs. Ambient Temperature

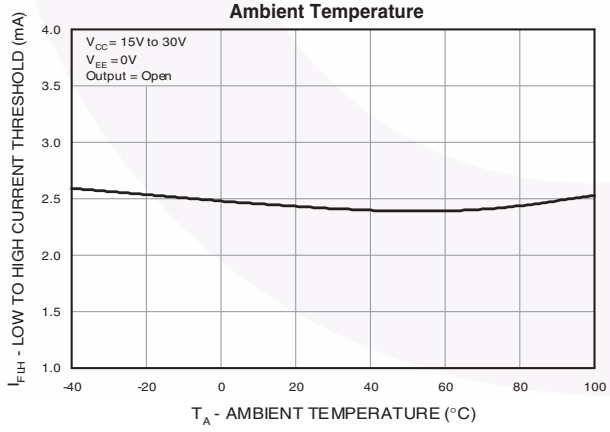
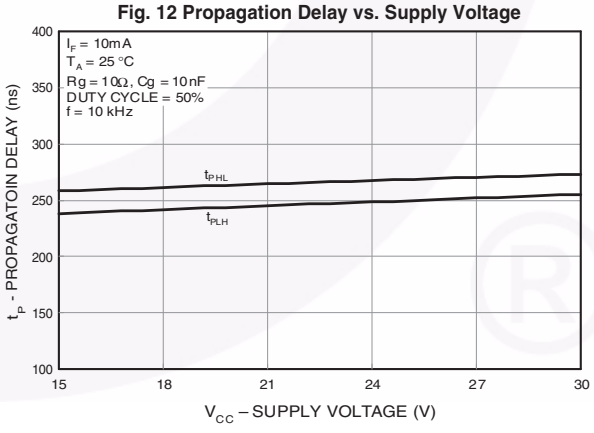


Fig. 12 Propagation Delay vs. Supply Voltage



Typical Performance Curves (Continued)

Fig. 13 Propagation Delay vs. LED Forward Current

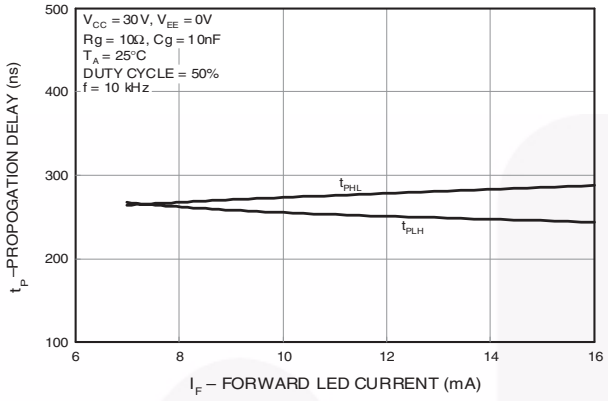


Fig. 14 Propagation Delay vs. Ambient Temperature

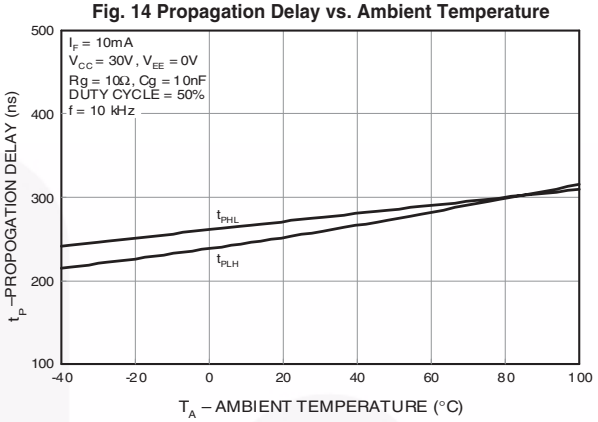


Fig. 15 Propagation Delay vs. Sereies Load Resistance

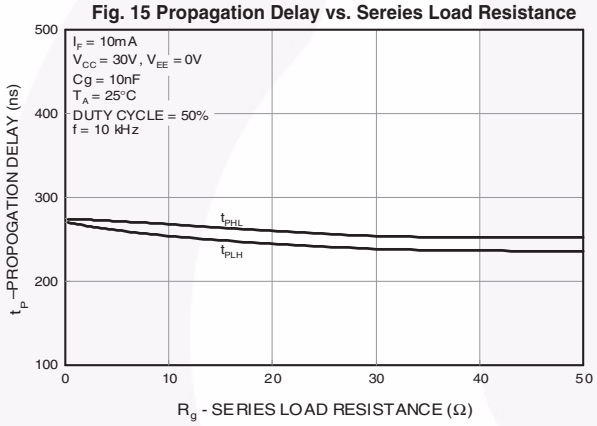


Fig. 16 Propagation Delay vs. Load Capacitance

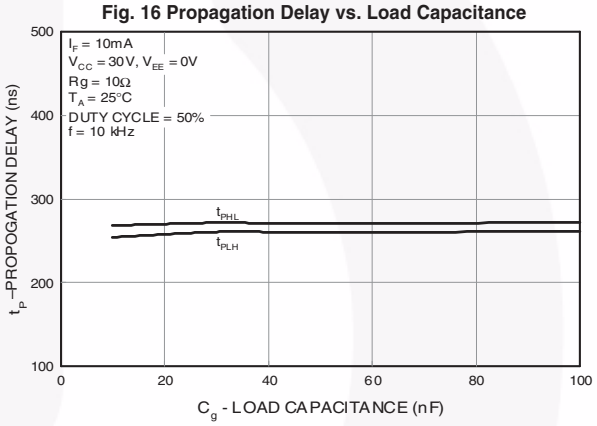


Fig. 17 Transfer Characteristics

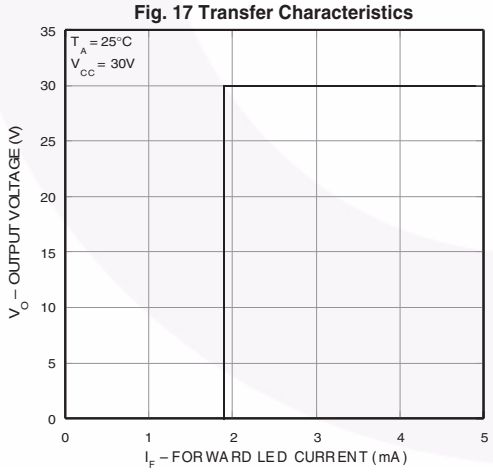
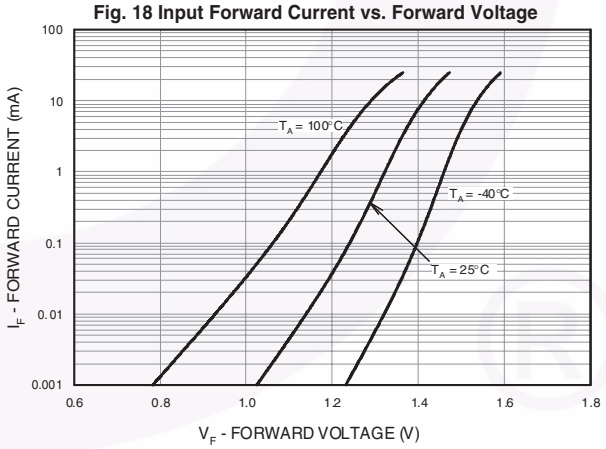
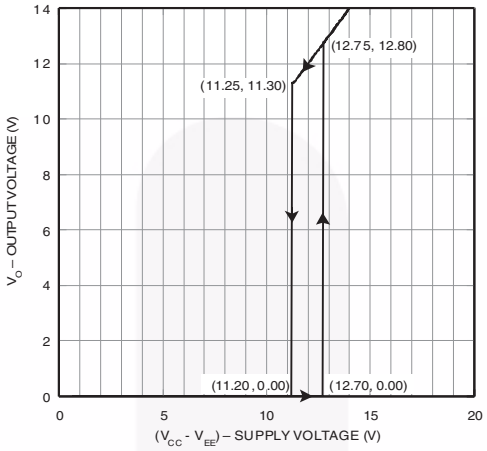


Fig. 18 Input Forward Current vs. Forward Voltage

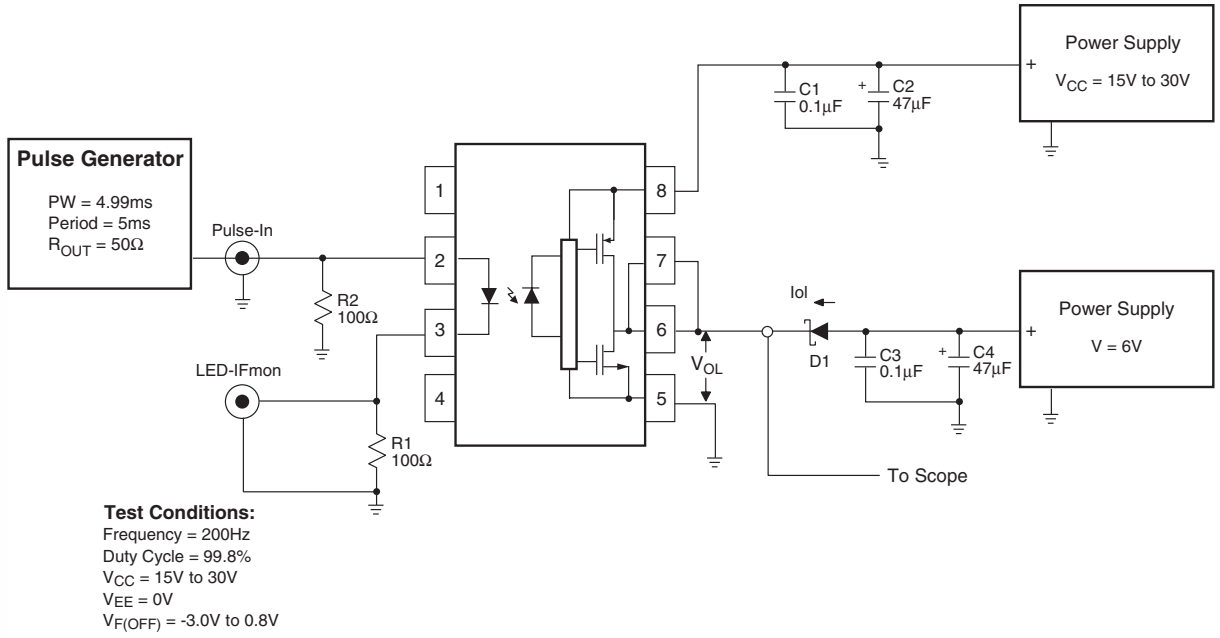


Typical Performance Curves (Continued)

Fig. 19 Under Voltage Lockout

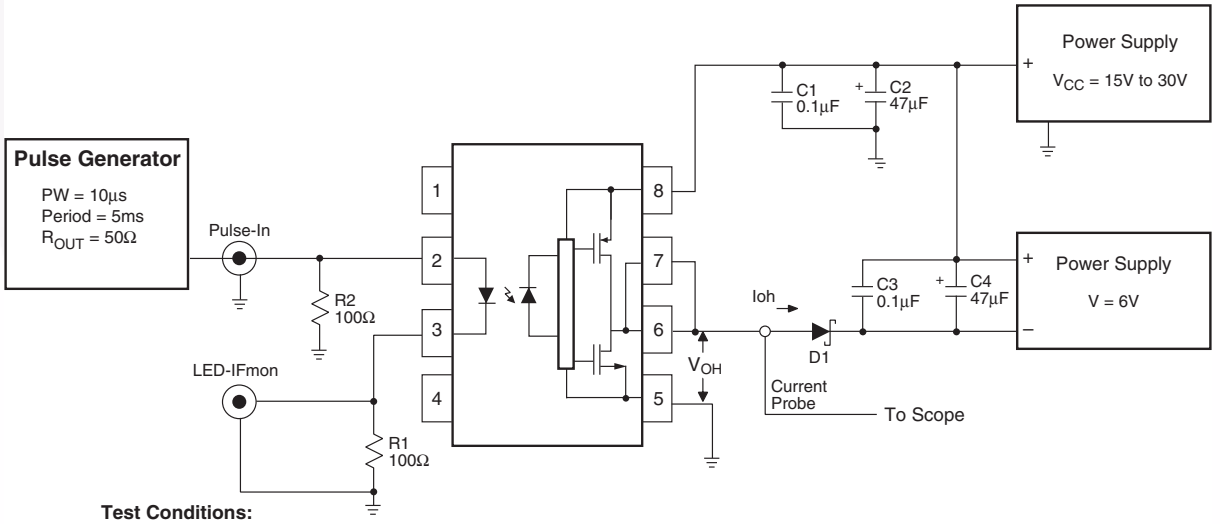


Test Circuit



Test Conditions:
Frequency = 200Hz
Duty Cycle = 99.8%
V_{CC} = 15V to 30V
V_{EE} = 0V
$V_{F(OFF)}$ = -3.0V to 0.8V

Figure 20. I_{OL} Test Circuit



Test Conditions:
Frequency = 200Hz
Duty Cycle = 0.2%
V_{CC} = 15V to 30V
V_{EE} = 0V
I_F = 7mA to 16mA

Figure 21. I_{OH} Test Circuit

Test Circuit (Continued)

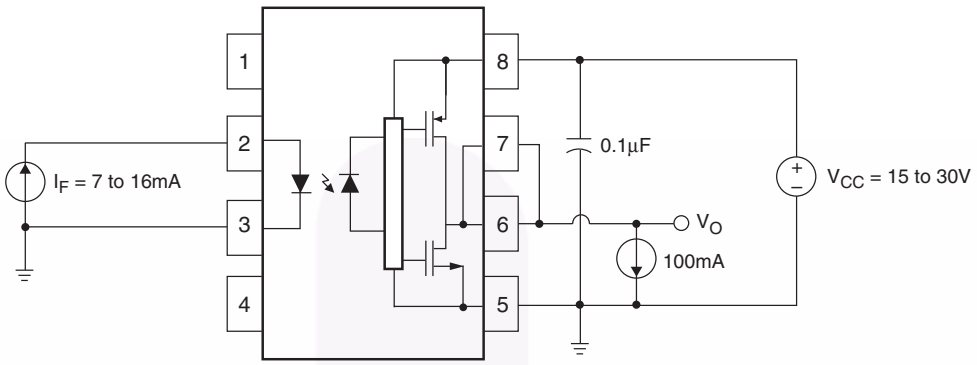


Figure 22. V_{OH} Test Circuit

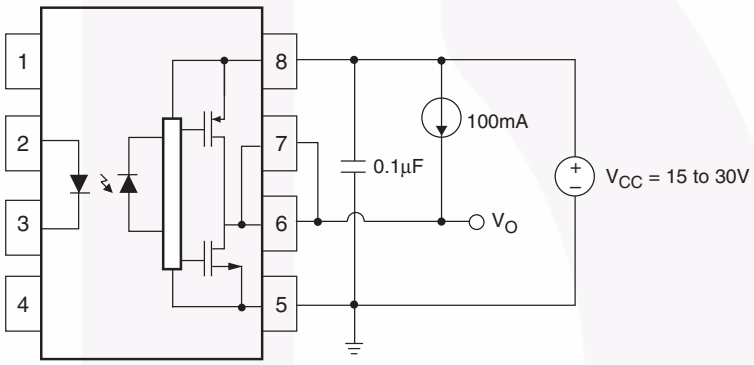


Figure 23. V_{OL} Test Circuit

Test Circuit (Continued)

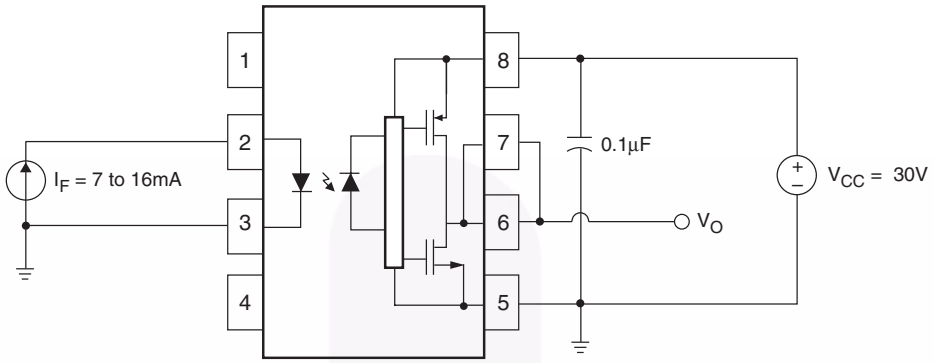


Figure 24. I_{CCH} Test Circuit

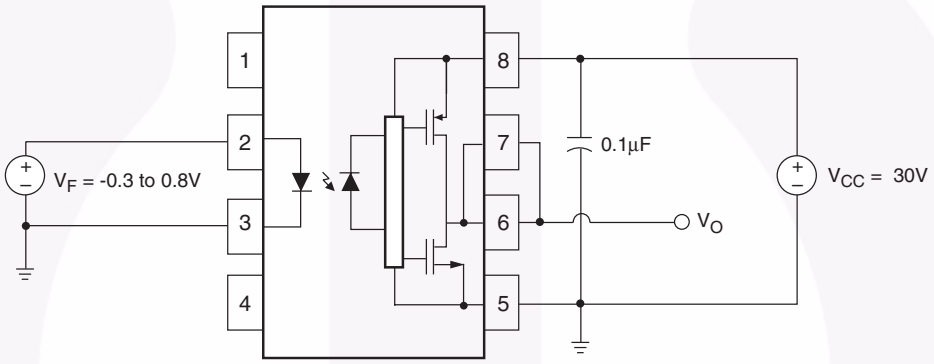


Figure 25. I_{CCL} Test Circuit

Test Circuit (Continued)

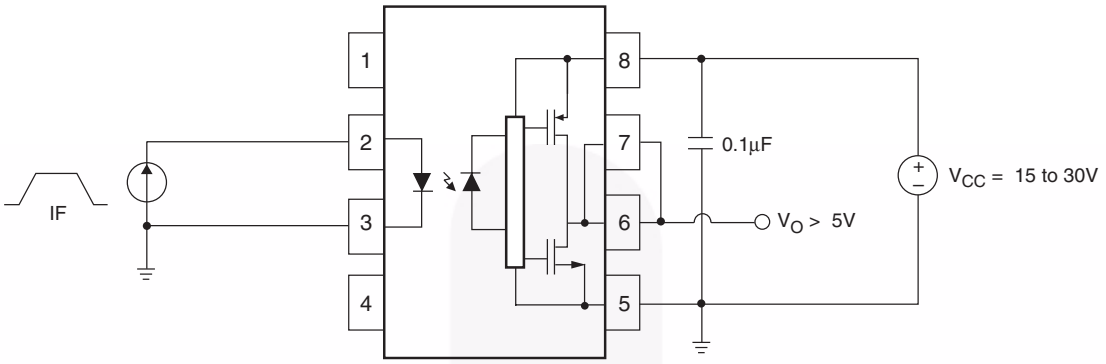


Figure 26. I_{FLH} Test Circuit

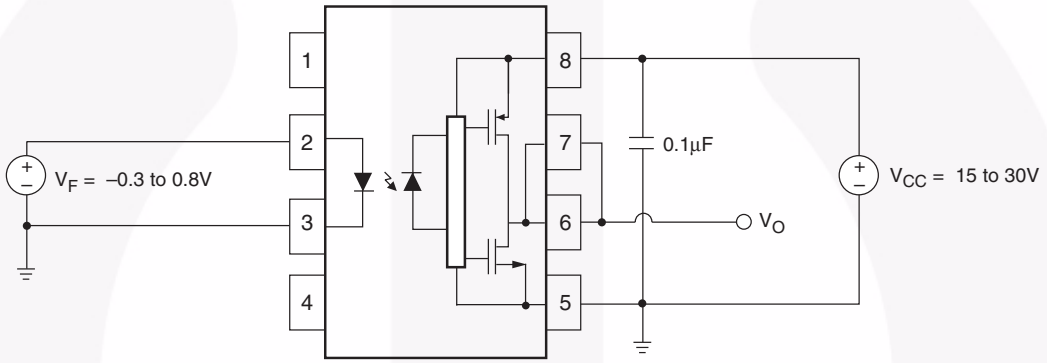


Figure 27. V_{FHL} Test Circuit

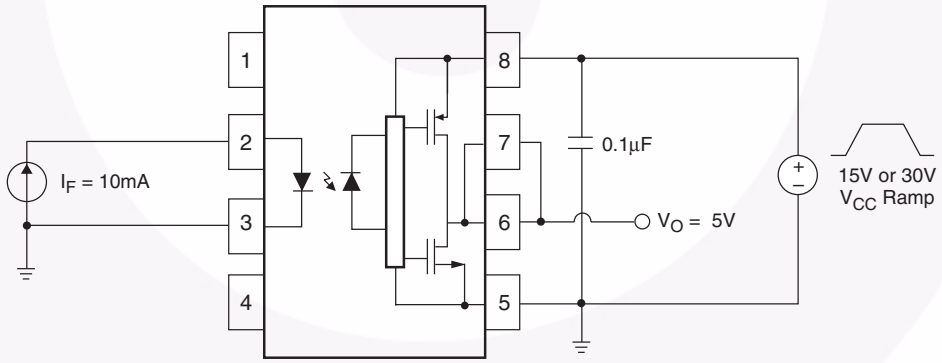


Figure 28. UVLO Test Circuit

Test Circuit (Continued)

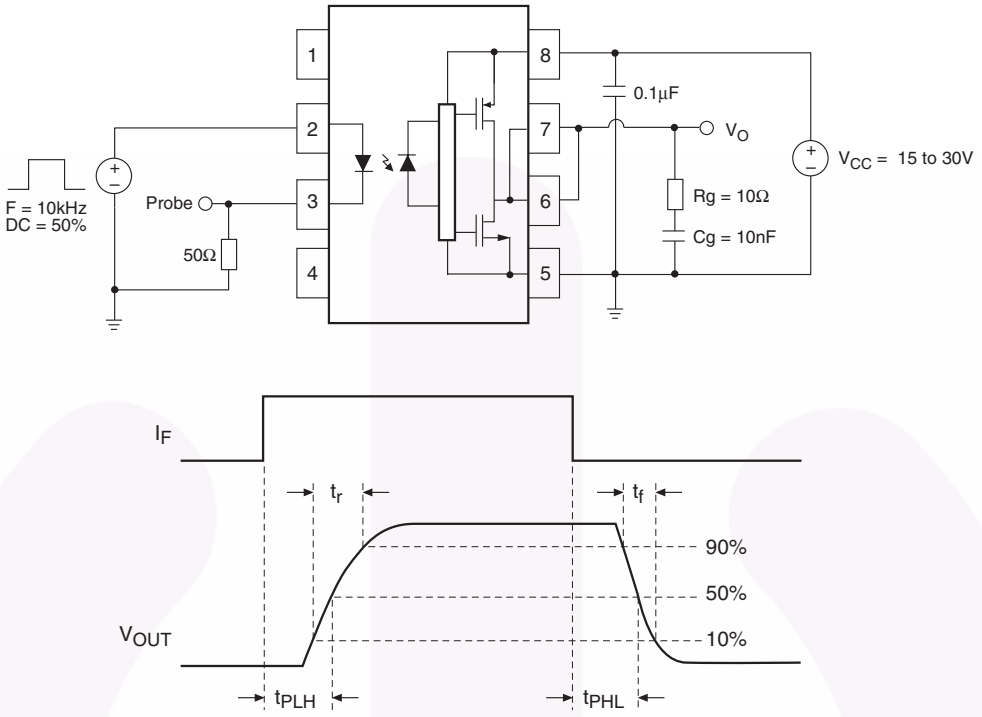


Figure 29. t_{PHL}, t_{PLH}, t_R and t_F Test Circuit and Waveforms

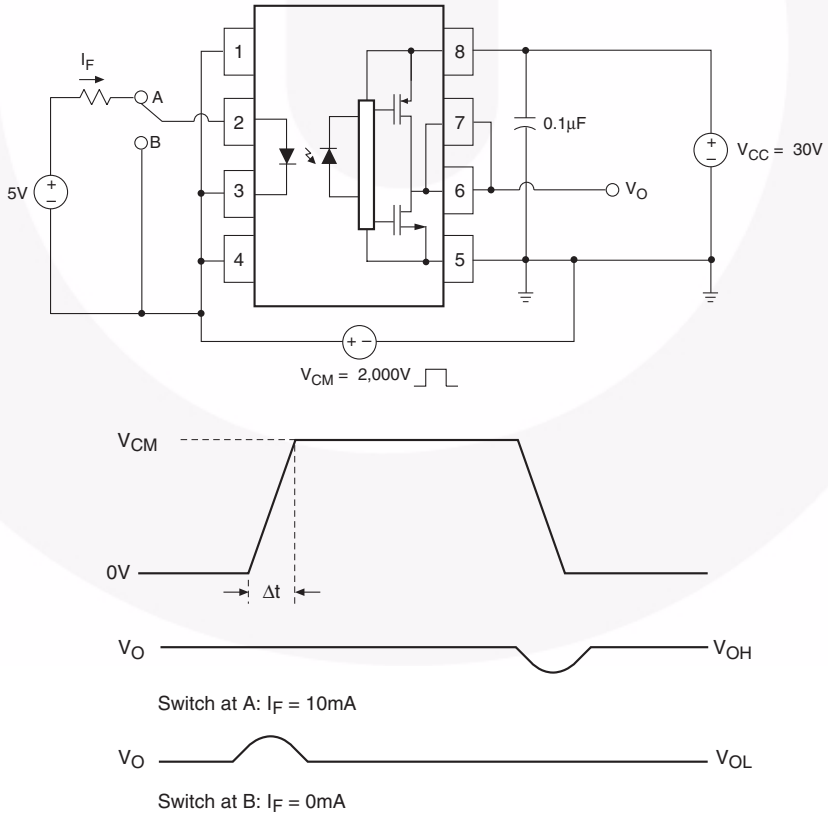
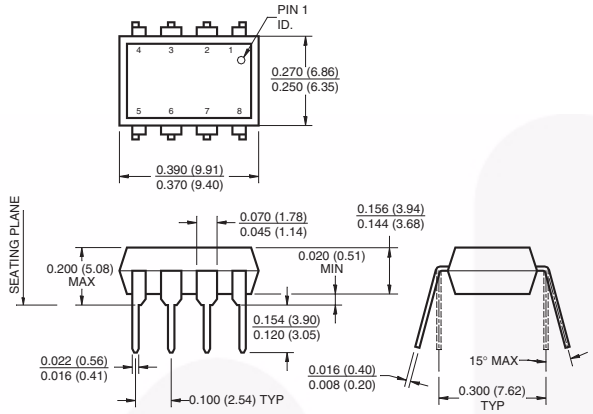


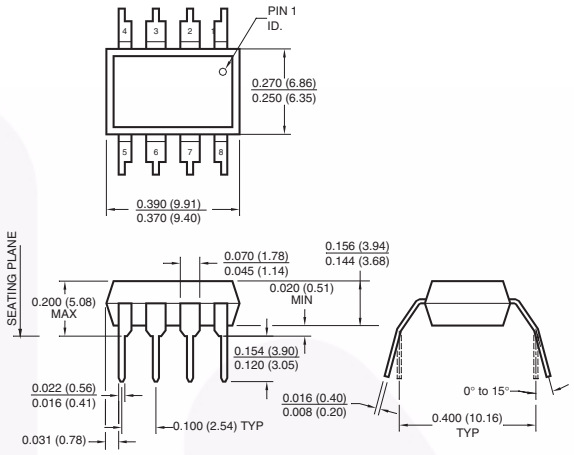
Figure 30. CMR Test Circuit and Waveforms

Package Dimensions

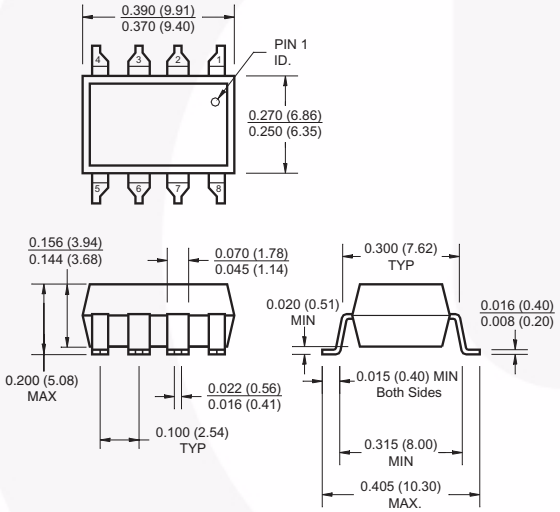
Through Hole



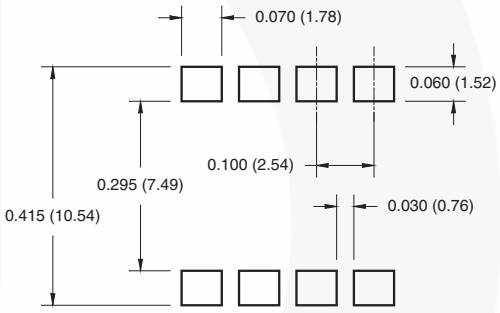
0.4" Lead Spacing (Option T)



Surface Mount – 0.3" Lead Spacing (Option S)



8-Pin Surface Mount DIP – Land Pattern (Option S)



Note:
All dimensions are in inches (millimeters)

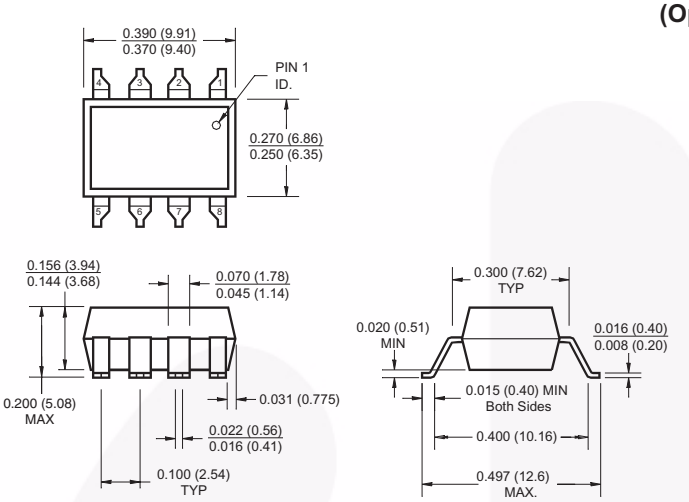
Package drawings are provided as a service to customers considering Fairchild components. Drawings may change in any manner without notice. Please note the revision and/or date on the drawing and contact a Fairchild Semiconductor representative to verify or obtain the most recent revision. Package specifications do not expand the terms of Fairchild's worldwide terms and conditions, specifically the warranty therein, which covers Fairchild products.

Always visit Fairchild Semiconductor's online packaging area for the most recent package drawings:

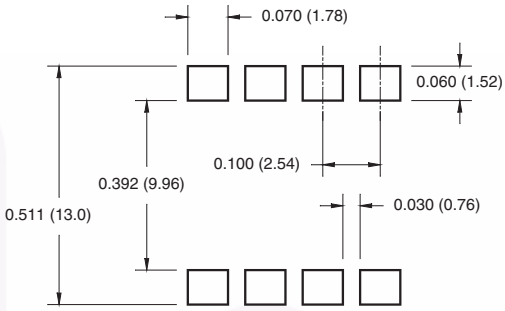
http://www.fairchildsemi.com/packaging/

Package Dimensions (Continued)

Surface Mount – 0.4" Lead Spacing (Option TS)



8-Pin Surface Mount DIP – Land Pattern (Option TS)



Note:
All dimensions are in inches (millimeters)

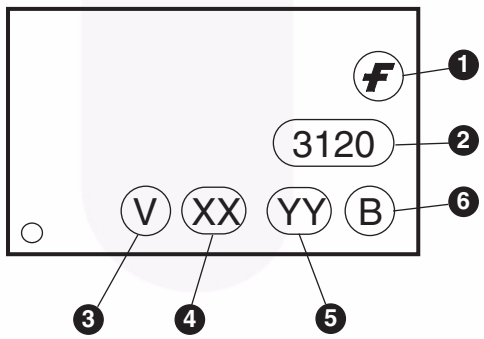
Package drawings are provided as a service to customers considering Fairchild components. Drawings may change in any manner without notice. Please note the revision and/or date on the drawing and contact a Fairchild Semiconductor representative to verify or obtain the most recent revision. Package specifications do not expand the terms of Fairchild's worldwide terms and conditions, specifically the warranty therein, which covers Fairchild products.

Always visit Fairchild Semiconductor's online packaging area for the most recent package drawings:
http://www.fairchildsemi.com/packaging/

Ordering Information

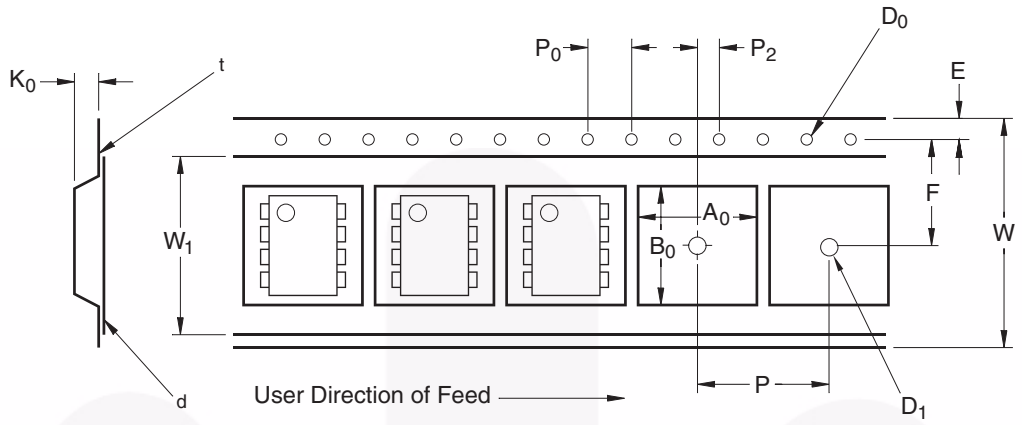
Part Number	Package	Packing Method
FOD3120	DIP 8-Pin	Tube (50 units per tube)
FOD3120S	SMT 8-Pin (Lead Bend)	Tube (50 units per tube)
FOD3120SD	SMT 8-Pin (Lead Bend)	Tape and Reel (1,000 units per reel)
FOD3120V	DIP 8-Pin, IEC60747-5-2 option	Tube (50 units per tube)
FOD3120SV	SMT 8-Pin (Lead Bend), IEC60747-5-2 option	Tube (50 units per tube)
FOD3120SDV	SMT 8-Pin (Lead Bend), IEC60747-5-2 option	Tape and Reel (1,000 units per reel)
FOD3120T	DIP 8-Pin, 0.4” Lead Spacing	Tube (50 units per tube)
FOD3120TV	DIP 8-Pin, 0.4” Lead Spacing , IEC60747-5-2 option	Tube (50 units per tube)
FOD3120TS	SMT 8-Pin, 0.4” Lead Spacing	Tube (50 units per tube)
FOD3120TSV	SMT 8-Pin, 0.4” Lead Spacing , IEC60747-5-2 option	Tube (50 units per tube)
FOD3120TSR2	SMT 8-Pin, 0.4” Lead Spacing	Tape and Reel (750 units per reel)
FOD3120TSR2V	SMT 8-Pin, 0.4” Lead Spacing , IEC60747-5-2 option	Tape and Reel (750 units per reel)

Marking Information



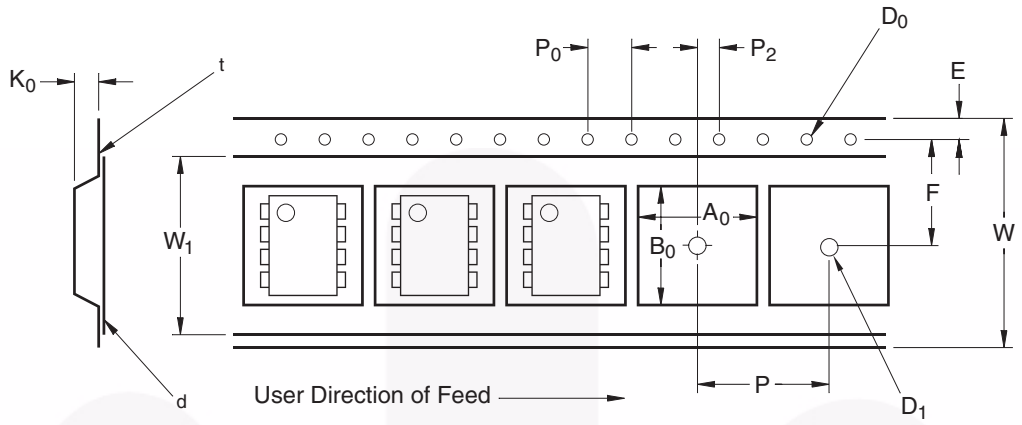
Definitions	
1	Fairchild logo
2	Device number
3	IEC60747-5-2 Option (only appears on component ordered with this option) (Pending approval)
4	Two digit year code, e.g., ‘08’
5	Two digit work week ranging from ‘01’ to ‘53’
6	Assembly package code

Carrier Tape Specifications (Option SD)



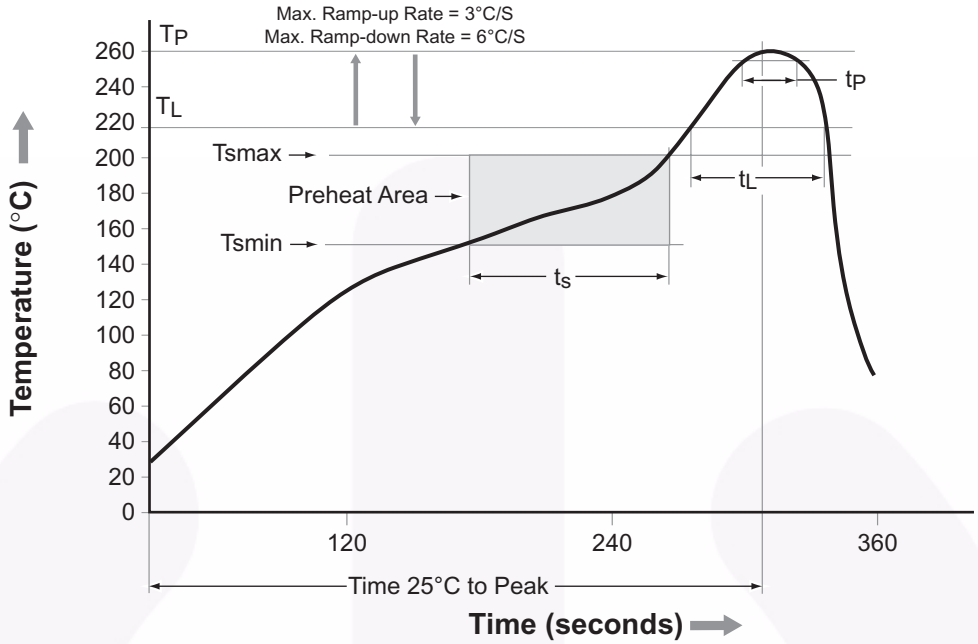
Symbol	Description	Dimension in mm
W	Tape Width	16.0 ± 0.3
t	Tape Thickness	0.30 ± 0.05
P_0	Sprocket Hole Pitch	4.0 ± 0.1
D_0	Sprocket Hole Diameter	1.55 ± 0.05
E	Sprocket Hole Location	1.75 ± 0.10
F	Pocket Location	7.5 ± 0.1
P_2		2.0 ± 0.1
P	Pocket Pitch	12.0 ± 0.1
A_0	Pocket Dimensions	10.30 ±0.20
B_0		10.30 ±0.20
K_0		4.90 ±0.20
W_1	Cover Tape Width	13.2 ± 0.2
d	Cover Tape Thickness	0.1 max
	Max. Component Rotation or Tilt	10°
R	Min. Bending Radius	30

Carrier Tape Specifications (Option TSR2)



Symbol	Description	Dimension in mm
W	Tape Width	24.0 ± 0.3
t	Tape Thickness	0.40 ± 0.1
P_0	Sprocket Hole Pitch	4.0 ± 0.1
D_0	Sprocket Hole Diameter	1.55 ± 0.05
E	Sprocket Hole Location	1.75 ± 0.10
F	Pocket Location	11.5 ± 0.1
P_2		2.0 ± 0.1
P	Pocket Pitch	16.0 ± 0.1
A_0	Pocket Dimensions	12.80 ± 0.1
B_0		10.35 ± 0.1
K_0		5.7 ±0.1
W_1	Cover Tape Width	21.0 ± 0.1
d	Cover Tape Thickness	0.1 max
	Max. Component Rotation or Tilt	10°
R	Min. Bending Radius	30

Reflow Profile



Profile Feature	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	150°C
Temperature Max. (Tsmax)	200°C
Time (t_S) from (Tsmin to Tsmax)	60–120 seconds
Ramp-up Rate (t_L to t_P)	3°C/second max.
Liquidous Temperature (T_L)	217°C
Time (t_L) Maintained Above (T_L)	60–150 seconds
Peak Body Package Temperature	260°C +0°C / –5°C
Time (t_P) within 5°C of 260°C	30 seconds
Ramp-down Rate (T_P to T_L)	6°C/second max.
Time 25°C to Peak Temperature	8 minutes max.

FAIRCHILD SEMICONDUCTOR®

TRADEMARKS

The following includes registered and unregistered trademarks and service marks, owned by Fairchild Semiconductor and/or its global subsidiaries, and is not intended to be an exhaustive list of all such trademarks.

Auto-SPM™
Build it Now™
CorePLUS™
CorePOWER™
CROSSVOLT™
CTL™
Current Transfer Logic™
EcoSPARK®
EfficentMax™
EZSWITCH™*
E²CMOS™*
ƒ®
Fairchild®
Fairchild Semiconductor®
FACT Quiet Series™
FACT®
FAST®
FastvCore™
FETBench™
FlashWriter®*
FPS™
F-PFS™
FRFET®
Global Power Resource℠
Green FPS™
Green FPS™ e-Series™
G*max*™
GTO™
IntelliMAX™
ISOPLANAR™
MegaBuck™
MICROCOUPLER™
MicroFET™
MicroPak™
MillerDrive™
MotionMax™
Motion-SPM™
OPTOLOGIC®
OPTOPLANAR®
PDP SPM™
Power-SPM™
PowerTrench®
PowerXS™
Programmable Active Droop™
QFET®
QS™
Quiet Series™
RapidConfigure™
™
Saving our world, 1mW/W/kW at a time™
SmartMax™
SMART START™
SPM®
STEALTH™
SuperFET™
SuperSOT™-3
SuperSOT™-6
SuperSOT™-8
SupreMOS™
SyncFET™
Sync-Lock™
SYSTEM GENERAL®*
The Power Franchise®
the power franchise
TinyBoost™
TinyBuck™
TinyLogic®
TINYOPTO™
TinyPower™
TinyPWM™
TinyWire™
TriFault Detect™
TRUECURRENT™*
µSerDes™
µSerDes™
UHC®
Ultra FRFET™
UniFET™
VCX™
VisualMax™
XS™

* Trademarks of System General Corporation, used under license by Fairchild Semiconductor.

DISCLAIMER

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION, OR DESIGN. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS. THESE SPECIFICATIONS DO NOT EXPAND THE TERMS OF FAIRCHILD'S WORLDWIDE TERMS AND CONDITIONS, SPECIFICALLY THE WARRANTY THEREIN, WHICH COVERS THESE PRODUCTS.

LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR CORPORATION.

As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury of the user.
2. A critical component in any component of a life support, device, or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

ANTI-COUNTERFEITING POLICY

Fairchild Semiconductor Corporation's Anti-Counterfeiting Policy. Fairchild's Anti-Counterfeiting Policy is also stated on our external website, www.fairchildsemi.com, under Sales Support.

Counterfeiting of semiconductor parts is a growing problem in the industry. All manufacturers of semiconductor products are experiencing counterfeiting of their parts. Customers who inadvertently purchase counterfeit parts experience many problems such as loss of brand reputation, substandard performance, failed applications, and increased cost of production and manufacturing delays. Fairchild is taking strong measures to protect ourselves and our customers from the proliferation of counterfeit parts. Fairchild strongly encourages customers to purchase Fairchild parts either directly from Fairchild or from Authorized Fairchild Distributors who are listed by country on our web page cited above. Products customers buy either from Fairchild directly or from Authorized Fairchild Distributors are genuine parts, have full traceability, meet Fairchild's quality standards for handling and storage and provide access to Fairchild's full range of up-to-date technical and product information. Fairchild and our Authorized Distributors will stand behind all warranties and will appropriately address any warranty issues that may arise. Fairchild will not provide any warranty coverage or other assistance for parts bought from Unauthorized Sources. Fairchild is committed to combat this global problem and encourage our customers to do their part in stopping this practice by buying direct or from authorized distributors.

PRODUCT STATUS DEFINITIONS

Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative / In Design	Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
Obsolete	Not In Production	Datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.

Rev. I40